

03-26-2002

Form PTO 1595



EET U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

To the Honorable Commissic

102030368

rd the attached original documents or copy thereof

1. Name of conveying parties:  
Nayon Tomsio  
Avi Liebermensch  
Execution Date: December 12, 2001  
Additional names of conveying Parties attached?  Yes  No

3-18-02

2. Name and address of receiving parties:  
Name: Sun Microsystems, Inc.  
Internal Address: M/S UPAL01-521  
Street Address: 901 San Antonio Road  
City: Palo Alto State: CA Zip: 94303  
Additional Names & Addresses attached?  Yes  No

3. Nature of conveyance;  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other  
Execution Date: See Above

4. Application number: 10/028,814  
If this document is being filed together with a new application, the execution date of the application is: herewith  
For: Resistive Vias for Controlling Impedance and Terminating I/O Signals at the Package Level  
A. Patent Application No. 10/028,814; filed Dec, 20, 2001 B. Patent No.(s)  
Additional Numbers attached?  Yes  No

OFFICE OF PUBLIC RECORDS  
702 MAR 18 PM 2:00  
FINANCE SECTION

5. Name and address of party to whom correspondence concerning this document should be mailed:  
Name: Kenneth C. Brooks  
Internal Address: Law Office of Kenneth C. Brooks  
Street Address: P. O. Box 10417  
City: Austin State: TX Zip: 78766

6. Total number of applications and patent involved: 1  
7. Total Fee (37 CFR 3.41) \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account  
8. Deposit Account Number:  
(Attach duplicate copy of this page if paying by deposit account)

Do Not Use This Space

9. Statement and signature.  
To the best of my knowledge and belief, the foregoing information is true and any attached copy is a true copy of the original document.  
Kenneth C. Brooks, Reg. No. 38,393  
Name of Person Signing *Kenneth C. Brooks* Signature *March 5, 2002* Date

10. Total number of pages comprising cover sheet, attachments, and document: 3

Mail documents to be recorded with the required cover sheet information to:  
Commissioner of Patents and Trademarks, Box Assignment  
Washington, D.C. 20231

03/26/2002 GTOW11 00000031 10028814  
01 FC:581 40.00 DP

**ASSIGNMENT FOR APPLICATION FOR PATENT**

WHEREAS:

Names and Addresses of Inventors:

1)	Nayon Tomsio 11416 Charred Oak Drive Austin, Texas 78759	2)	Avi Liebermensch 1115 Elmsford Drive Cupertino, California 95014
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(hereinafter referred to as Assignors), have invented a certain invention entitled:

**RESISTIVE VIAS FOR CONTROLLING IMPEDANCE AND TERMINATING I/O SIGNALS AT THE PACKAGE LEVEL**

for which application for Letters Patent in the United States

having serial number \_\_\_\_\_, filed herewith and for which a declaration was executed on \_\_\_\_\_; and

WHEREAS, Sun Microsystems, Inc., a corporation of the State of Delaware, having a place of business at 901 San Antonio Road, Palo Alto, California 94303 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Assignors hereby authorize and request the attorneys of record to insert, where indicated above, the application number and filing date of said application when known.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) Dec. 12, 2001   
Nayon Tomsio

2) \_\_\_\_\_, 2001 \_\_\_\_\_  
Avi Liebermensch

**ASSIGNMENT FOR APPLICATION FOR PATENT**

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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- 1) \_\_\_\_\_, 2001 \_\_\_\_\_  
Nayon Tomsio
- 2) 12/12, 2001 \_\_\_\_\_  
Avi Liebermensch